

REMARKS

This is in response to the Office Action that was mailed on October 28, 2006. Claim 1 is amended to recite the feature of claim 3, and claim 3 is accordingly cancelled. Claim 13 is amended to recite the feature of claim 15, and claim 15 is accordingly cancelled. Claims 1 and 13 are also amended to clarify the “receiving surface” aspect of the invention. New claims 17 and 18 correspond to original claims 1 and 3 and 13 and 15, respectively. Finally, claim 11 and the specification are amended to address the issues with respect to the trademark TEFLON. Claims 1-2, 4-14, and 16-18 are pending in this application.

Objection was raised to the specification, and claim 11 was rejected under 35 USC § 112, due to their use of the trademark TEFLON. Both the specification and claim 11 have been amended to obviate the objection and rejection. These amendments are merely clarifying, non-narrowing claim amendments.

Claims 1 and 13 were rejected under the second paragraph of 35 USC § 112 as failing to define the invention properly. The Examiner requested clarification regarding the recitation of the terminology “receiving surface” in the claims. Claims 1 and 13 have been amended to specify that the organic thin-film layer of the transfer material faces only the side of the substrate having the transparent conductive layer formed thereon being intended to form a receiving surface. It is respectfully submitted that the claims as amended satisfy the requirements of the statute.

Claims 1-16 were rejected under 35 U.S.C. §102(b) as being anticipated by US 6,194,119 B1 to Wolk et al. (“Wolk”). It is noted that the Wolk patent corresponds to WO 00/41893, which is discussed on page 3 of Applicant’s specification.

Distinguishing features of the present invention include the steps of: (1) heating and/or pressing a transfer material having an organic thin-film layer formed on a temporary support and a first laminate comprising a substrate and at least a transparent conductive layer or a rear-surface electrode formed on the substrate, which overlap each other such that the organic thin-film layer of the transfer material faces only the side of the substrate having the transparent conductive layer formed thereon, thereby forming a laminate structure; and (2) heating and/or pressing which is carried out by at least one of a laminator, an infrared heater, or a roller heater.

In contrast to the present invention, Wolk discloses a method for thermally transferring an organic thin-film layer and a photo-thermal conversion layer onto a substrate by *a laser beam* by using a donor sheet having an organic thin-film layer and a photo-thermal conversion layer. Such a thermal transfer method is disadvantageous in that a gas often penetrates into an interface between the organic thin-film layer and the substrate. In contrast to the present invention, Wolk does not suggest, for instance, the use of an infrared heater. Wolk teaches donor elements including three components of a substrate, an optional light-to-heat conversion layer (LTHC layer), and a single or multi-component transfer layer that can be image-wise transferred to a receptor to form an organic electroluminescent device. The LTHC layer containing a radiation absorber is indispensable to convert light energy including infrared, visible, and ultraviolet lasers to heat energy. See Wolk: column 6, lines 27-39; column 6, line 60 – column 7, line 5; and the Examples (Nd:YAG laser; violet, 1.06 μm).

Specifically, Wolk teaches a method for patterning a first material and a second material on a receptor by selectively and simultaneously thermally transferring the first material adjacent to the second material on the receptor donor using, e.g., an infrared laser, thereby providing organic electroluminescent devices having the transferred, patterned structure. See Wolk: claim 2; column 4, lines 29-45. The use of a laser beam as in Wolk necessitates the use of the LTHC layer, thereby increasing the components in the layer structure of the organic electroluminescent device, which increase translates to a decrease in productivity. The Wolk laser also necessitates a large apparatus, in order to ensure protection against exposure to the laser beam. Also, in producing a pattern material with a laser beam, there is the necessity to transfer a whole of the size and the shape of a pattern material for a relatively long time, thereby shortening the life of

the costly laser beam source by applying high power energy thereto. This too adversely affects productivity, from the viewpoint of increased time and cost of the Wolk process.

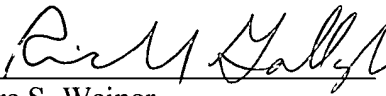
In contrast to Wolk, the transfer material of the present invention comprises two components of an organic thin-film layer and a temporary support, on which the organic thin-film layer is adhered without using a LTHC layer. In this invention, the transfer of the whole of the size and the shape of a pattern material of the organic thin-film layer for producing a surface emitting device is performed by heating by heating and/or pressing with at least one of a laminator, an infrared heater, and a roller heater. See the specification, page 5, lines 5-8. This produces a surface emitting device which has excellent light-emitting efficiency with high productivity at a low cost, and the organic thin-film layer provided by the present invention is much thinner than that obtained by a thermal transfer method using a laser, resulting in excellent uniformity of light emission. See the specification, page 46, lines 21-17.

Nothing in the Wolk disclosure teaches or suggests these beneficial features of the presently claimed invention. Withdrawal of the rejection of record and passage of this application to Issue is respectfully solicited.

Should there be any questions, the Examiner is respectfully requested to contact Richard Gallagher (Reg. No. 28,781) at (703) 205-8008.

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Respectfully submitted,

By  #28,781
for Marc S. Weiner
Registration No. 32,181
BIRCH, STEWART, KOLASCH & BIRCH, LLP
8110 Gatehouse Rd
Falls Church, Virginia 22040-0747
(703) 205-8000
Attorney for Applicant